HOSTAFORM® XGC10 EF XAP®2

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Hostaform® XGC10 EF XAP®2 is an easy flowing injection molding grade reinforced with approximately 10% glass fibers, and has reduced emissions.
Emissions according to VDA 275 < 5 ppm [mg/kg].

Product information

Resin Identification	POM-GF10	ISO 1043
Part Marking Code	>POM-GF10<	ISO 11469

Rheological properties

Melt volume-flow rate	12	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.1	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	4900	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	110	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	4	%	ISO 527-1/-2
Flexural modulus	4700	MPa	ISO 178
Charpy impact strength, 23°C	60	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6.5	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.35[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	154	°C	ISO 75-1/-2

Flammability

Burning rate, Thickness 1 mm	81	mm/min	ISO 3795 (FMVSS 302)

Physical/Other properties

Density	1480	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C

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Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa
Ejection temperature	138	°C

Characteristics

Processing	Injection Moulding
Special characteristics	High Flow, Low emissions

Automotive

OEM	ADDITIONAL INFORMATION
VW Group	No Spec, Special Part Approval, See Your CE Account Manager.

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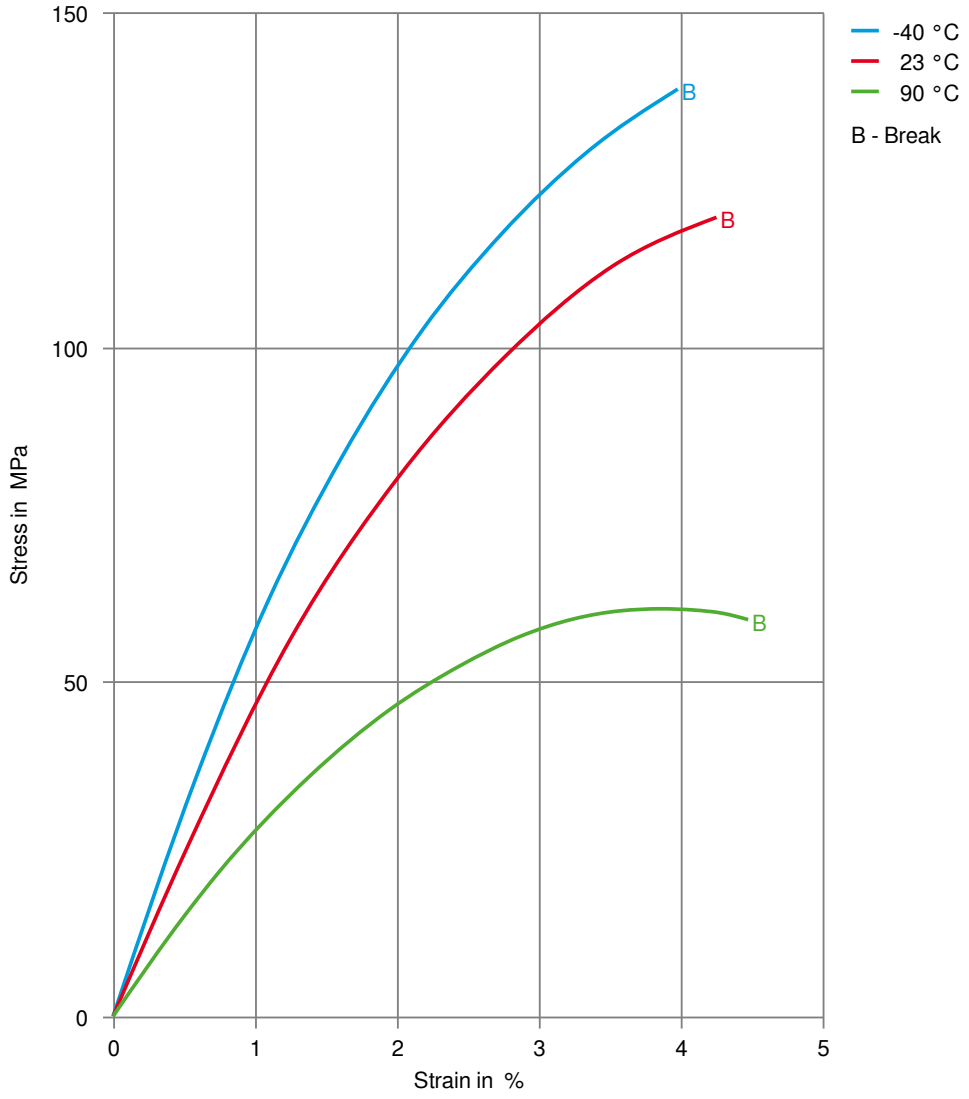
Stress-strain



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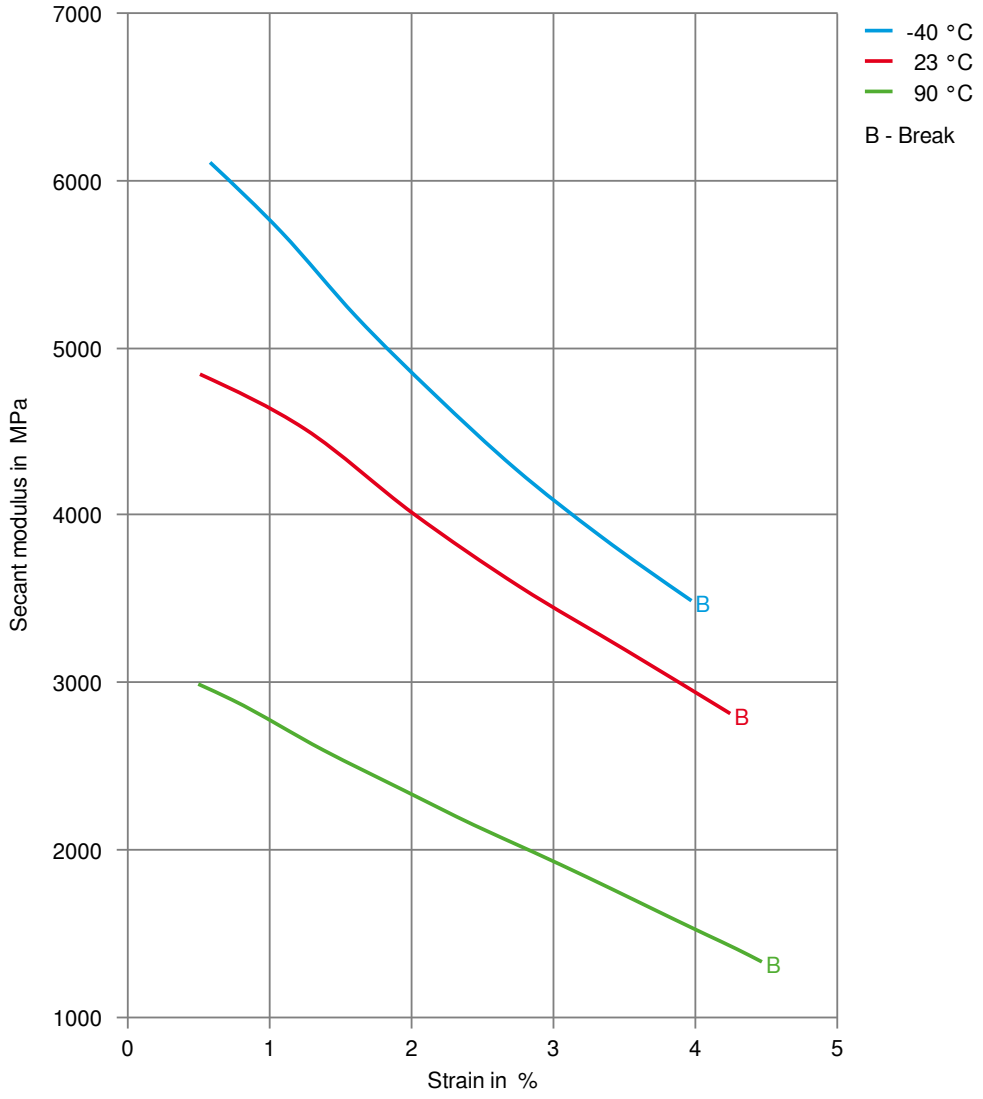
Secant modulus-strain



Revised: 2024-07-12 Source: Celanese Materials Database